

FIG. 1
(PRIOR ART)

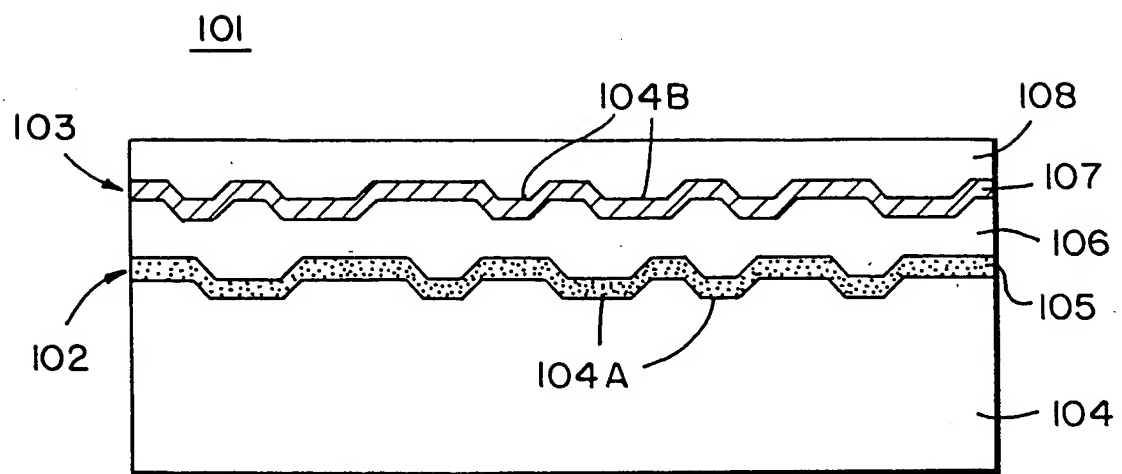


FIG. 2(A)
(PRIOR ART)

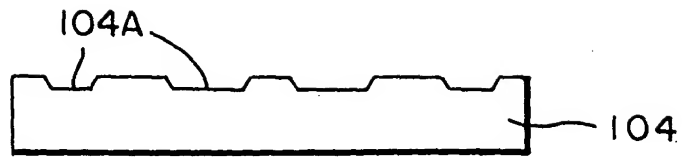


FIG. 2(B)
(PRIOR ART)

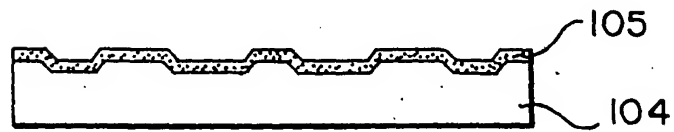


FIG. 2(C)
(PRIOR ART)

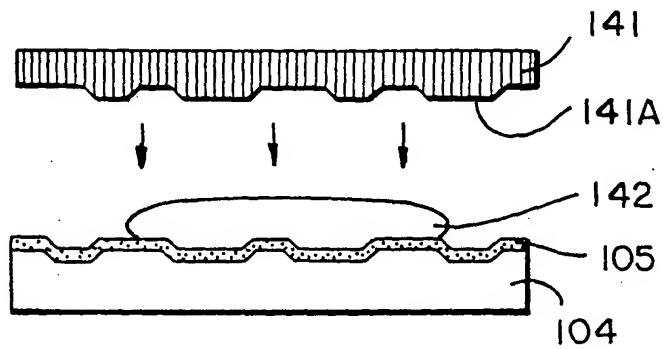


FIG. 2(D)
(PRIOR ART)

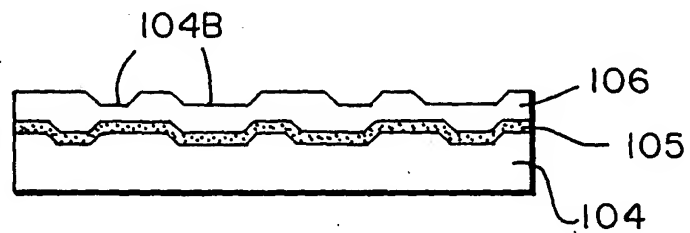


FIG. 2(E)
(PRIOR ART)

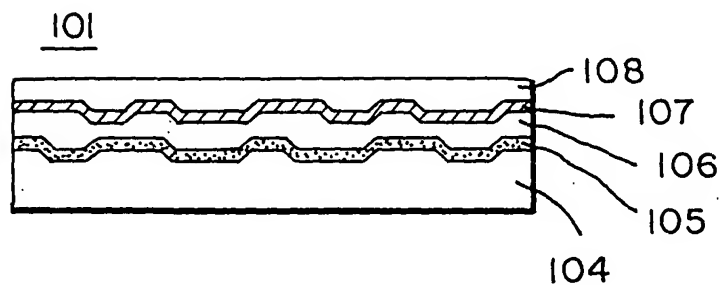


FIG. 4(A)




FIG. 4(A) is a cross-sectional view of a substrate 4 with a series of rectangular protrusions 4A on its top surface.

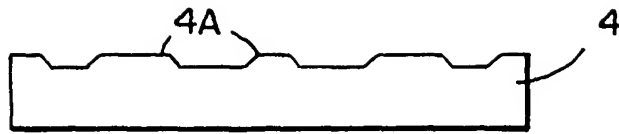



FIG. 4(B)



A cross-sectional view of a device. It features a base layer labeled 4 and a top layer labeled 5. The top layer 5 has a wavy, undulating surface profile. The base layer 4 is a solid, uniform layer beneath the top layer.

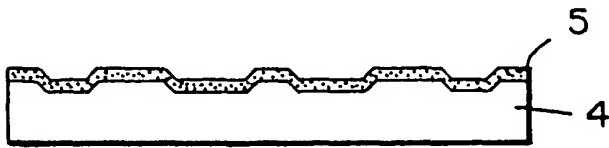


FIG. 4(C)

34

36

36A

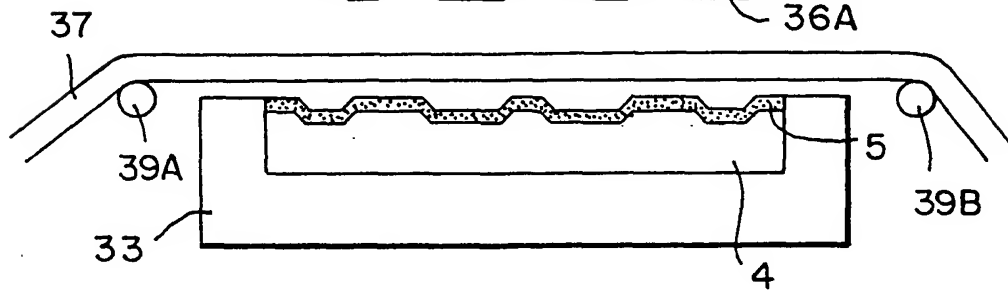
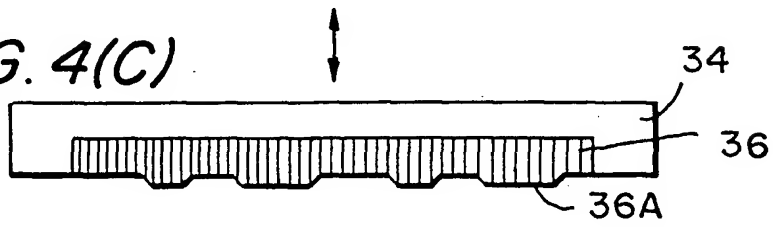


FIG. 4(D)

FIG. 4(D) is a cross-sectional view of a fourth embodiment of the device. It shows a substrate 4 with a layer 5 on top. Layer 5 has a series of rectangular protrusions 6. A layer 4B is formed on top of layer 5, filling the recesses between the protrusions 6.

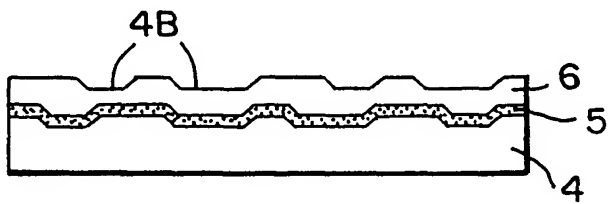


FIG. 4(E)

FIG. 4(E) is a cross-sectional view of a device. It shows a substrate 4 with a layer 5. Layer 5 contains a series of rectangular features 6. Above layer 5 is a layer 7, and above layer 7 is a layer 8. The features 6 are filled with a material indicated by diagonal hatching.

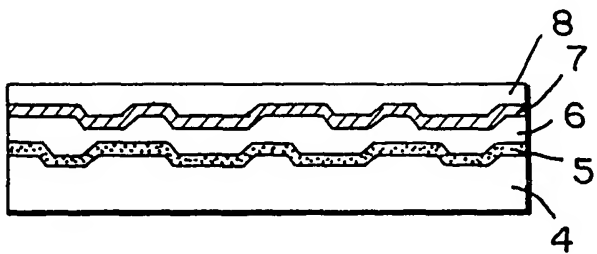


FIG. 7(A)

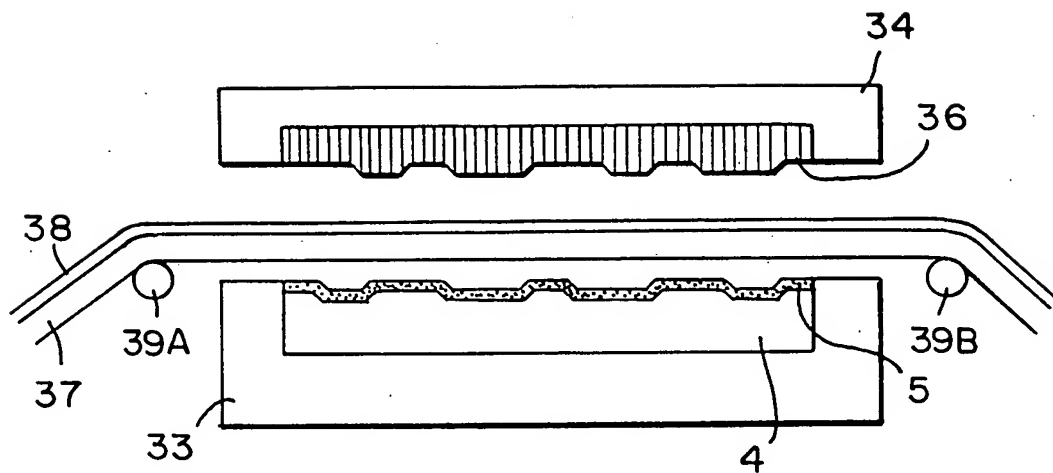


FIG. 7(B)

